

Events at a Glance

| 15 June 2010 (Tue) | 16 June 2010 (Wed) | 17 June 2010 (Thur) |
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| NEPCON Malaysia 2010 - Penang 10am to 6pm • PISA | | |
| Opening Ceremony 9am <i>All are welcome</i> | NEPCON Malaysia 2011 - Penang Space Reservation 10:30am - 5:00pm | NEPCON Malaysia 2011 - Penang Space Reservation 10:30am - 5:00pm |
| The hazards of solder dross and its solutions presented by Mr. Yan Yongnong, Shenzhen Kunqi Xinhua Technology Co., Ltd. 11:00am - 11:45am Technology Forum | The digital solution for excellent Power Quality presented by Alan Huan, Imaxtech Electronics Sdn Bhd 11:00am - 11:45am Technology Forum | |
| Business Intelligence in Supply Chain Management presented by Mr Sandeep Basu, Enterprise Solutions of ECnet Ltd 2:00pm - 2:45pm Technology Forum | Business Without Borders presented by Mr Tarun Mathur, ECnet Ltd 2:00pm - 2:45pm Technology Forum | Optimizing Vendor Managed Inventory in Lean Manufacturing presented by Mr Vincent Tey, ECnet Malaysia 2:00pm - 2:45pm Technology Forum |
| Challenges to Next Generation SMT Process Control presented by Mr. Masanori Ikeda, Panasonic Industrial Company 2:45pm - 3:30pm Technology Forum | | |
| Basler ace - the smallest size, the newest technology, and the best price for a GigE Vision camera presented by Derek Chan, Basler Asia Pte Ltd 3:30pm - 4:15pm Technology Forum | | An eco system for design engineering presented by Farnell Newark 4:15 - 5:00pm Technology Forum |
| Opening Party 6:00pm - 8:00pm <i>All are welcome</i> | | |
| NEPCON series of workshops - organized by Knowledge Group of Companies 8:30am to 5:00pm • Equatorial Hotel | | |
| Workshop A SMT Manufacturing in the New Decade - Material, Process, Reliability (Part 1) By Dr. Jennie Hwang, H-Technologies Group, USA | Workshop B SMT Manufacturing in the New Decade - Material, Process, Reliability (Part 2) By Dr. Jennie Hwang, H-Technologies Group, USA | Workshop C Solar Energy in Electronics Industry - An Overview By Dr. Jennie Hwang, H-Technologies Group, USA |
| Workshop D Integrated Circuit Packaging and Assembly By Dr. Thomas Dory, Arizona State University, USA | Workshop E Semiconductor Device and Assembly Manufacturing By Dr. Thomas Dory, Arizona State University, USA | |
| Workshop F Halogen-Free Printed Circuit Board Materials By Bhanu Sood, University of Maryland's Center for Advanced Life Cycle Engineering (CALCE), USA | Workshop G Component Authentication and Screening By Bhanu Sood, University of Maryland's Center for Advanced Life Cycle Engineering (CALCE), USA | Workshop I Failure Modes and Effect Analysis By Bong Kong Liang, Applied Breakthrough Technologies, Malaysia |
| Workshop H Lean Six Sigma Manufacturing Implementation By Bong Kong Liang, Applied Breakthrough Technologies, Malaysia | | |
| Workshop J IPC-A-610D Acceptability of Electronic Assemblies By A. Vijayendra, Industry Association Training Centre (IATC), India | | |